















# MULTILAYER CHIP INDUCTOR

# SMI SERIES

## Electrical Specification

Size 1008 High Current Type

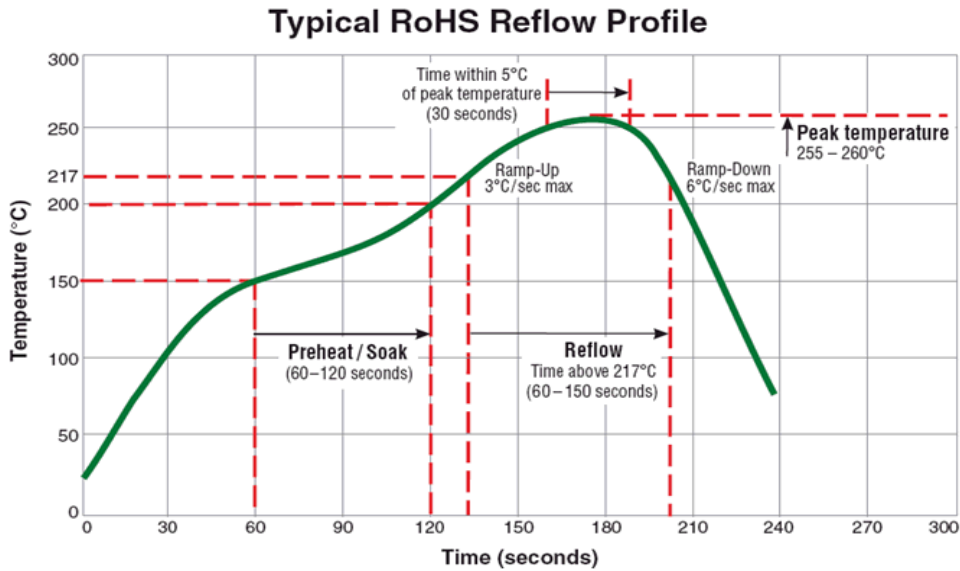
Part No.	Inductance (uH)	Tolerance	Test Condition	SRF (MHz) min.	DCR (Ω) max.	IDC (mA) max.
SMI1008HTR47□□□	0.47	±20%	1MHz, 250mV	100	0.088	1800
SMI1008HTR68□□□	0.68	±20%	1MHz, 250mV	90	0.113	1700
SMI1008HTR82□□□	0.82	±20%	1MHz, 250mV	80	0.125	1700
SMI1008HT1R0□□□	1.0	±20%	1MHz, 250mV	60	0.138	1600
SMI1008HT1R2□□□	1.2	±20%	1MHz, 250mV	60	0.138	1600
SMI1008HT1R5□□□	1.5	±20%	1MHz, 250mV	50	0.163	1500
SMI1008HT1R8□□□	1.8	±20%	1MHz, 250mV	50	0.163	1500
SMI1008HT2R2□□□	2.2	±20%	1MHz, 250mV	40	0.213	1300
SMI1008HT3R3□□□	3.3	±20%	1MHz, 250mV	30	0.200	1200
SMI1008HT4R7□□□	4.7	±20%	1MHz, 250mV	25	0.250	1100

■ Operating Temperature: -40°C to +125°C



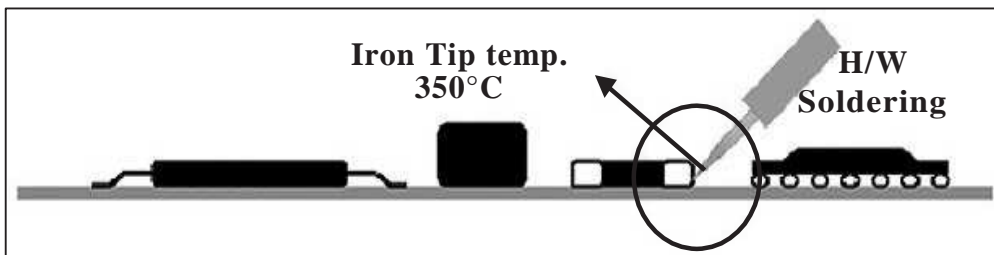
■ **Soldering Profile**

**Reflow Soldering**



**Manual Soldering**

Soldering iron tip temperature: 350°C max / within 3 seconds.



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## Environmental Characteristics

### Mechanical Performance Test

Item	Requirement	Test Method
Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal. Electrode should be covered with solder. Inductance: within $\pm 15\%$ of initial value Q: within $\pm 30\%$ of initial value Inductance: within $\pm 20\%$ of initial value (0603 over 12uH)	Pre-heating: 150°C, 1 min. Solder Composition: Sn/Ag3.0/Cu0.5 (Pb-Free) Solder Temperature: 260 $\pm$ 5°C (Pb-Free) Immersion Time: 10 $\pm$ 1 sec.
Solderability	The electrodes shall be at least 90% covered with new solder coating	Pre-heating: 150°C, 1 min. Solder Composition: Sn/Ag3.0/Cu0.5 (Pb-Free) Solder Temperature: 245 $\pm$ 5°C (Pb-Free) Immersion Time: 4 $\pm$ 1 sec.
Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite.	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6 mm Deflection: 2.0 mm Keeping Time: 30 sec. *For 0402, substrate dimension is 100x40x0.8 mm
Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1 min. Amplitude: 1.5 mm Time: 2 hrs for each axis (X, Y & Z), total 6 hrs

### Electrical Performance Test

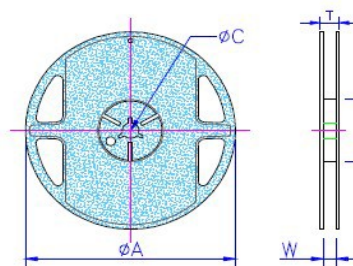
Item	Requirement	Test Method
Inductance	Refer to standard electrical characteristic spec.	HP4291B
Q		HP4291B
SRF		HP4291B
DC Resistance RDC		Agilent 34401A
Rated Current IDC		Applied the current to coils, The inductance change should be less than 10% to initial value

### Climatic Test

Item	Requirement	Test Method															
Damp Heat with Load	Appearance: No damage L change: within $\pm 10\%$ of initial value Q change: within $\pm 30\%$ of initial value	Temperature: 40 $\pm$ 2°C Relative Humidity: 90 ~ 95% Time: 1000 hrs Measured after exposure in the room condition for 24 hrs															
Temperature Cycle		One cycle: <table border="1"> <thead> <tr> <th>Step</th> <th>Temperature (°C)</th> <th>Time (min.)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-40<math>\pm</math>3</td> <td>30</td> </tr> <tr> <td>2</td> <td>25<math>\pm</math>2</td> <td>3</td> </tr> <tr> <td>3</td> <td>85<math>\pm</math>3</td> <td>30</td> </tr> <tr> <td>4</td> <td>25<math>\pm</math>2</td> <td>3</td> </tr> </tbody> </table> Total: 100 cycles Measured after exposure in the room condition for 24 hrs	Step	Temperature (°C)	Time (min.)	1	-40 $\pm$ 3	30	2	25 $\pm$ 2	3	3	85 $\pm$ 3	30	4	25 $\pm$ 2	3
Step		Temperature (°C)	Time (min.)														
1		-40 $\pm$ 3	30														
2	25 $\pm$ 2	3															
3	85 $\pm$ 3	30															
4	25 $\pm$ 2	3															
High Temperature Resistance	Temperature: 85 $\pm$ 3°C Relative Humidity: 20% Applied Current: Rated Current Time: 1000 hrs Measured after exposure in the room condition for 24 hrs																
Low Temperature Resistance	Temperature: -25 $\pm$ 3°C Relative Humidity: 0% Time: 1000 hrs Measured after exposure in the room condition for 24 hrs																

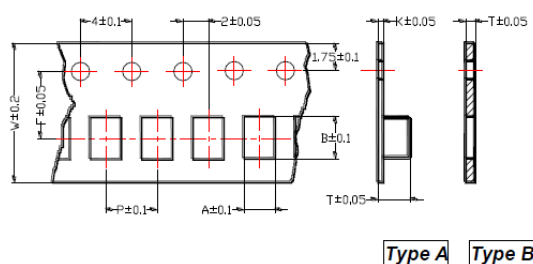
## ■ Packaging

### Reel Specifications



Type	A (mm)	B mm	C mm	W mm	T mm	Quantity (EA)	
						Paper Tape (Type B)	Polystyrene Tape (Type A)
SMI0603F	178±1	60.0±0.5	13.0±0.2	9.00±0.5	12.0±0.15	4,000	-
SMI0805F(≤2.2uH)	178±1	60.0±0.5	13.0±0.2	9.00±0.5	12.0±0.15	4,000	-
SMI0805F(≥2.7uH)	178±1	60.0±0.5	13.0±0.2	9.00±0.5	12.0±0.15	-	3,000
SMI1206F	178±1	60.0±0.5	13.0±0.2	9.00±0.5	12.0±0.15	-	3,000
SMI0805H	178±1	60.0±0.5	13.0±0.2	9.00±0.5	12.0±0.15	4,000	-
SMI0806H	178±1	60.0±0.5	13.0±0.2	9.00±0.5	12.0±0.15	-	3,000
SMI1008H	178±1	60.0±0.5	13.0±0.2	9.00±0.5	12.0±0.15	-	3,000

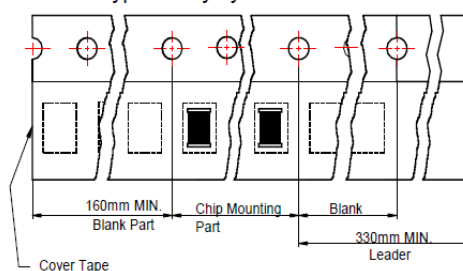
### Taping Specifications



### Tape Material

Carrier tape: Polystyrene for 0805(≤2.2uH) 1206  
Paper for 0603 0805(≥2.7uH)

Cover type: Polystyrene



Type	A mm	B mm	T mm	W mm	P mm	F mm	K mm	Tape Type
SMI0603F	1.05	1.85	0.95	8.0	4.0	3.5	-	B
SMI0805F(≤2.2uH)	1.50	2.42	0.95	8.0	4.0	3.5	-	B
SMI0805F(≥2.7uH)	1.50	2.35	1.45	8.0	4.0	3.5	0.22	A
SMI1206F	1.88	3.50	1.27	8.0	4.0	3.5	0.22	A
SMI0805H	1.45	2.25	0.95	8.0	4.0	3.5	-	B
SMI0806H	1.88	2.40	1.23	8.0	4.0	3.5	0.23	A
SMI1008H	2.20	2.85	1.40	8.0	4.0	3.5	0.23	A